

# PER-TAIX2-A10-2280

## Thermal Image Analysis Report

Summary	<input type="checkbox"/> <b>Pass</b> <input type="checkbox"/> <b>Fail</b> <input checked="" type="checkbox"/> <b>Pass with Deviation</b> <b>Comment:</b> <u>There is one temperature point marginal passed, the system works properly.</u>			
	<b>Test Result Summary</b>			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	1
Defect Unsolved	0	0	0	1

Issue date

2019 / 04 / 30

QE Supervisor

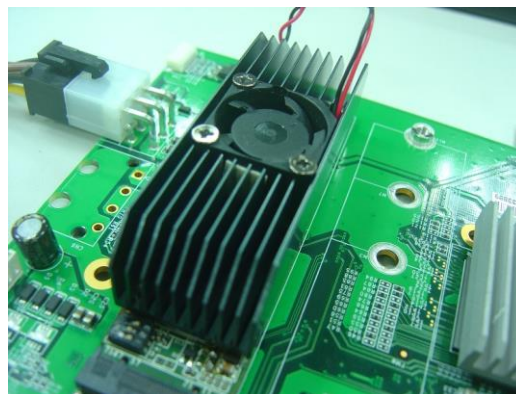
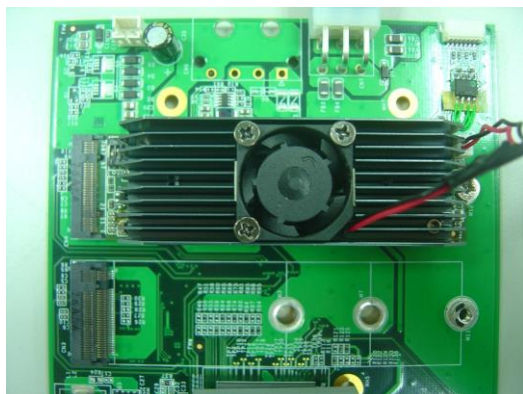
Louie Lee

Test Engineer

Ben Sun

## Sample Configuration & Quantity Under Test

- **Model name : PER-TAIX2-A10-2280**
- **PCI-E Riser Card : PER-TAIX2-A10-PCIE A0.2**
- **Main Board : SMS-002 R1.03**
  1. CPU : Intel Pentium G3260 / 3.3GHz
  2. Memory : Panram 8GB \* 1 / DDR3 1333 / F143X8ADW405
  3. 2.5" SSD : Transcend 32GB / SSD370
  4. BIOS : SMS-002 V1.6AddBraswellPatch.7
- **Test Software : Ubuntu 16.04.5 Kernel version : v4.15**  
**/ Run Open Vino version : R5.1**
- **Power : CWT DSA400P-C**
- **Cooler :**



# Thermal Image Analysis

1. Test Date: 2019-04-29

2. Test Product: PER-TAIX2-A10-2280 A0.2

3. Test Site: AAEON QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 YOKOGAWA Inc,

4.1.2 Model: DA100-13-1D

Date of Calibration: 09/07/18

Serial Number: 12A323190

4.2. IR Scanner: Infrared Camera

4.2.1 NEC Avio Infrared Technologies Co., Ltd.

4.2.2 Model: Thermo GEAR G100W2-D

Date of Calibration: 11/06/18

Serial Number: 1051444

5. Test Condition:

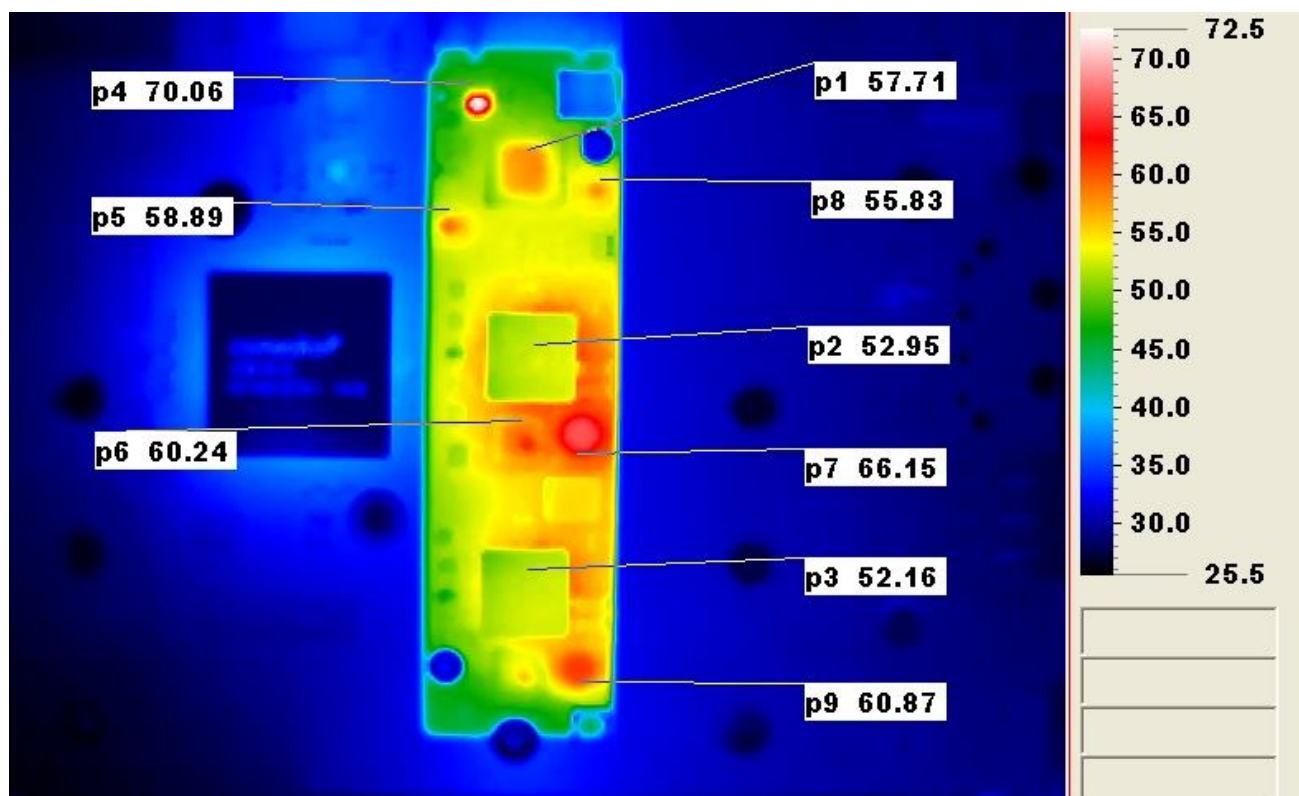
Test by DA-100: 25.0°C with Cooler

6. Take Picture Time:

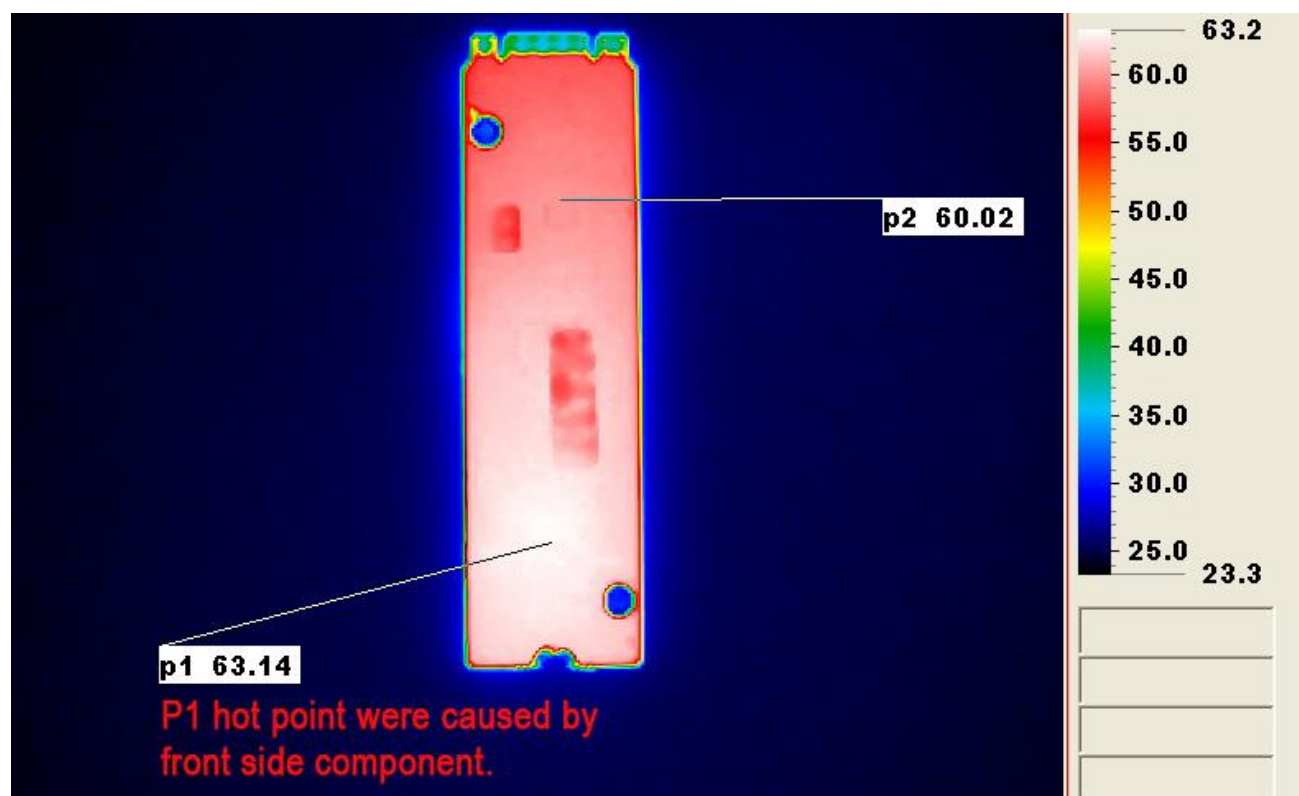
After power on 2 hours

# Temperature Profile Test:

Component Side:

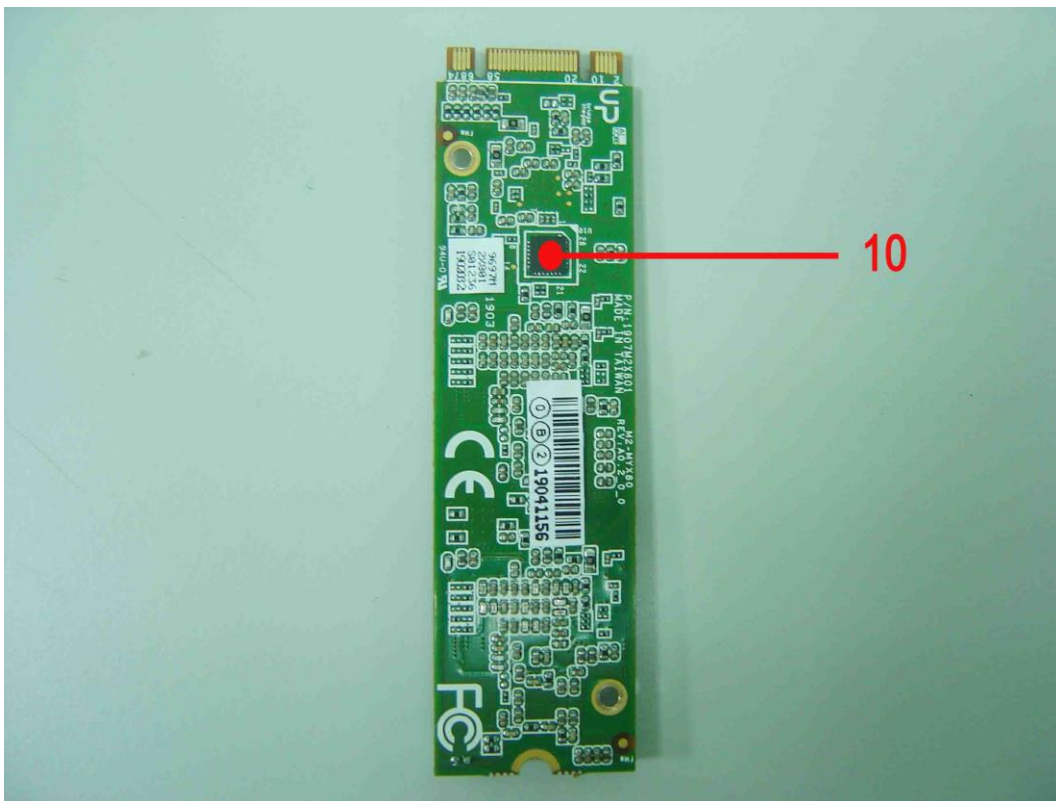
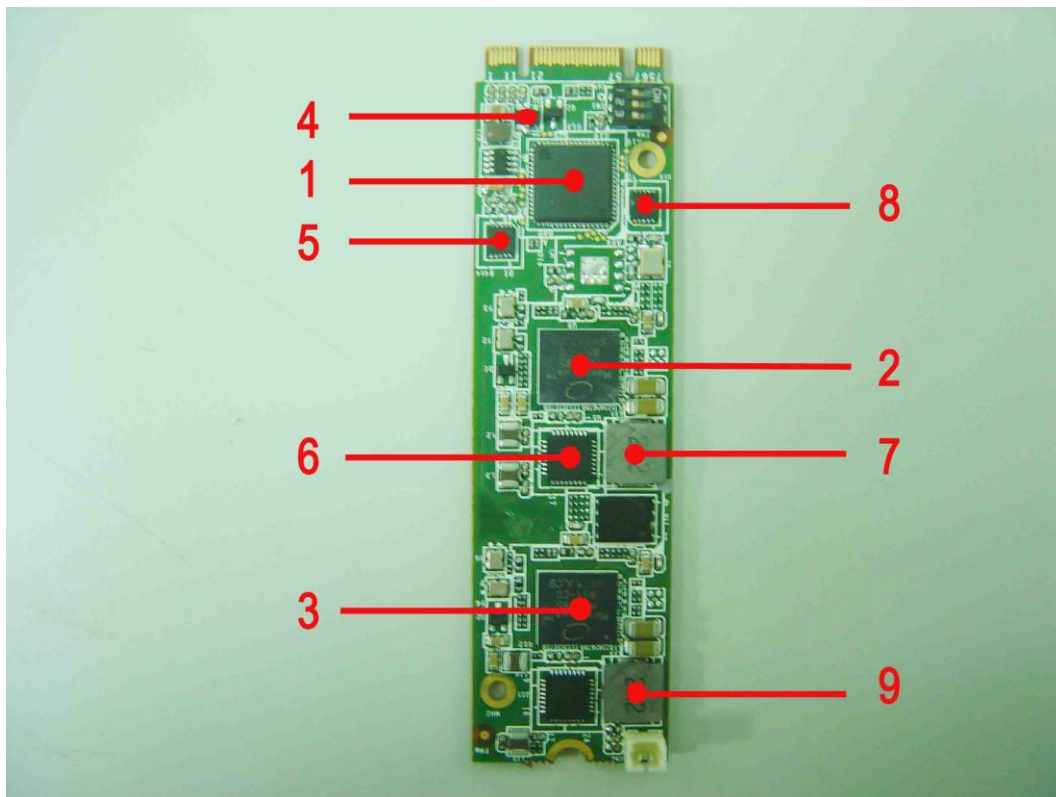


Back Side:



## Terminal Recorder:

Measuring Thermal Couple Position :



## Using YOKOGAWA / DA100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	TAT(*2)	TPT(*3)	Note
				25°C	60°C	
1	U13	(TF)IC.PCIE to 4 port USB3.0.Host Controller.DRQFN-116P.SMD.FRESCO.FL1100-1Q0-EX	105°C	61.0	96.0	
2	U6	(TF)IC.CHIPSET.VPU.MyriadX.VFBGA 380-ball.SMD.Movidius.MA2485(C0)/MM#999A6H/SLMYP	125°C	66.5	101.5	
3	U12	(TF)IC.CHIPSET.VPU.MyriadX.VFBGA 380-ball.SMD.Movidius.MA2485(C0)/MM#999A6H/SLMYP	125°C	61.0	96.0	
4	FB1	(TF)BEAD.60ohm(100MHz).3.5A.0603.SMD.TDK.MPZ1608S600 A	125°C	57.2	92.2	
5	U14	(TF)IC.ULDO Regulator.6V.3A.WDFN-10L 3x3.SMD.RICHTEK.RT9059GQW	100°C	56.5	91.5	
6	U3	(TF)IC.Triple Synchronous.Step-Down Converter.VQFN32.TI.TPS65266RHBR	125°C	70.3	105.3	
7	L11	(TF)COIL.2.2uH.DCR=58mΩ.Idc=4Amp.20%.SMD.7.1*6.6*1.0m m.RLITECH.AMPI0612ED2R2MT	125°C	75.4	110.4	
8	U15	(TF)IC.ULDO Regulator.6V.3A.WDFN-10L 3x3.SMD.RICHTEK.RT9059GQW	100°C	45.8	80.8	
9	L12	(TF)COIL.2.2uH.DCR=58mΩ.Idc=4Amp.20%.SMD.7.1*6.6*1.0m m.RLITECH.AMPI0612ED2R2MT	125°C	65.6	100.6	
10	U10	(TF)IC.USB to GPIO.Host Controller.QFN-28P.SMD.FINTEK.F75114N	85°C	48.0	83.0	NOTE4

## Note(\*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.

2. "TAT" indicates the actual measured temperature under product specification.

3. "TPT" indicates the predicted temperature under 25°C working environmental.

## 4. Judgment Criteria:

- Fail :  $T_m > T_c + 5^{\circ}\text{C}$ ; The measured value is over specification plus margin.- Margin :  $T_c + 5^{\circ}\text{C} > T_m > T_c - 10^{\circ}\text{C}$ ; The measured value is within specification with margin.

For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.

- Pass :  $T_m < T_c - 10^{\circ}\text{C}$ ; The measured value is with safety margin.

5. RTC battery avoid to put on heat position. Please do not exceed battery temperature specification.

Defect No: